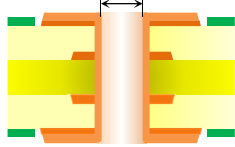
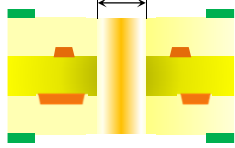
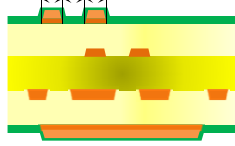
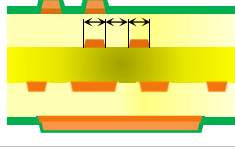
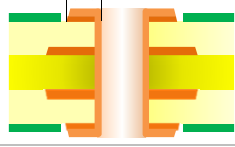
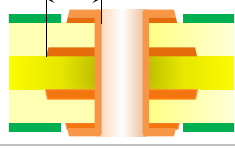
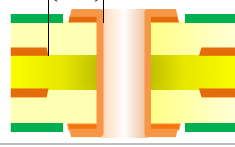
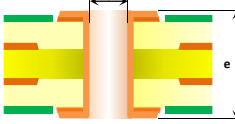




Class Table

Item	Class III	Class IV	Class V	Class VI	Class VII
Minimum Platted Through Hole (PTH) 	500 µm	300 µm	300 µm	200 µm	200 µm
Minimum Non Platted Through Hole (NPTH) 	600 µm	400 µm	400 µm	300 µm	300 µm
Width and isolation of copper conductors in outer layers (Base Copper) 	300 µm (17 µm)	200 µm (17 µm)	150 µm (17 µm)	125 µm (17 µm)	100 µm (17 µm)
	300 µm (35 µm)	200 µm (35 µm)	175 µm (35 µm)	150 µm (35 µm)	125 µm (35 µm)
	350 µm (70 µm)	250 µm (70 µm)	250 µm (70 µm)	250 µm (70 µm)	
Width and isolation of copper conductors in inner layers (Base Copper) 	250 µm (17 µm)	150 µm (17 µm)	125 µm (17 µm)	100 µm (17 µm)	100 µm (17 µm)
	300 µm (35 µm)	200 µm (35 µm)	150 µm (35 µm)	125 µm (35 µm)	100 µm (35 µm)
	300 µm (70 µm)	250 µm (70 µm)	250 µm (70 µm)	200 µm (70 µm)	
Copper annular ring for outer layers (Base Copper) 	225 µm (17 µm)	200 µm (17 µm)	150 µm (17 µm)	125 µm (17 µm)	100 µm (17 µm)
	225 µm (17 µm)	200 µm (35 µm)	175 µm (35 µm)	150 µm (35 µm)	125 µm (35 µm)
	275 µm (17 µm)	250 µm (70 µm)	250 µm (70 µm)	250 µm (70 µm)	
Copper annular ring for inner layers 	250 µm	220 µm	190 µm	170 µm	150 µm
Minimum isolation distance on inner layers (mass and power) 	400 µm	400 µm	300 µm	250 µm	250 µm
Aspect Ratio (máximum raw material thickness)  Aspect Ratio = e/d	8 (2,4 mm)	8 (2,4 mm)	8 (2,4 mm)	8 (2,4 mm)	8 (2,4 mm)
	5 (3,2 mm)	5 (3,2 mm)	5 (3,2 mm)	5 (3,2 mm)	5 (3,2 mm)

REMARKS

The pcb will become one class higher if at least one of the conditions of such a class is met